

1 WHAT IS CLAIMED IS

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1. A method of fabricating a semiconductor device, comprising the steps of:

forming an electronic circuit on a wafer in a region defined by a scribe line, said wafer carrying
10 a first electrode thereon;

attaching a circuit substrate carrying thereon a predetermined conductor pattern, on said wafer, said circuit substrate carrying a second electrode and a third electrode, said step of
15 attaching said circuit substrate including a step of aligning said circuit substrate with respect to said electronic circuit in said wafer;

interconnecting said first electrode on said wafer and second electrode of said predetermined
20 conductor pattern by a wire bonding process;

forming a spherical electrode on said third electrode; and

dicing said wafer along said scribe line.

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2. A method as claimed in claim 1, wherein said step of attaching including a step of bonding
30 said circuit substrate to said wafer by an adhesive.

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3. A method as claimed in claim 1, wherein said step of attaching said circuit substrate includes the steps of: placing said circuit substrate on said

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1 wafer; aligning said circuit substrate with respect to
said wafer; and lifting said circuit substrate in a
direction generally perpendicular to said wafer by
introducing a resin to a space between said wafer and
5 said circuit substrate.

10 4. A method as claimed in claim 1, further comprising a step of encapsulating a bonding wire used in said wire bonding step and said first and second electrodes by a resin.

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5. A method as claimed in claim 4, wherein
said step of dicing along said scribe line is
20 conducted along said resin.

25 6. A method as claimed in claim 1, further comprising a step of providing a resin along said scribe line, and wherein said step of dicing is conducted along said resin.

7. A method as claimed in claim 1, wherein said circuit substrate is formed of a polyimide tape carrying thereon a conductor pattern.

1 8. A method as claimed in claim 1, wherein
said circuit substrate is formed of a glass epoxy
carrying a conductor pattern.

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 9. A method as claimed in claim 1, wherein
said wire bonding process is conducted first by
10 bonding a first end of a bonding wire to said first
electrode on said wafer and subsequently by bonding a
second end of said bonding wire to said second
electrode on said circuit substrate.

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 10. A method as claimed in claim 1, wherein
said spherical electrode is formed by a solder bump.

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 11. A semiconductor device, comprising:
a semiconductor chip having a top surface,
said semiconductor chip carrying a first electrode;
a circuit substrate attached to a top
surface of said semiconductor chip, said circuit
substrate carrying thereon a predetermined conductor
30 pattern including a second electrode and a third
electrode;

a resin layer intervening between said top
surface of said semiconductor chip and said circuit
substrate;

35 a spherical electrode provided on said
circuit substrate in correspondence to said third
electrode;

1 a bonding wire electrically interconnecting
said second electrode of said predetermined conductor
pattern on said circuit substrate and said first
electrode on said semiconductor chip; and
5 a resin potting encapsulating said bonding
wire including said first and second electrodes,
said chip and said resin potting being
defined by a common edge surface substantially
perpendicular to a principal surface of said
10 substrate.

15 12. A semiconductor device as claimed in
claim 11, wherein said resin layer is an adhesive
layer.

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13. A semiconductor device as claimed in
claim 11, wherein said resin layer has a composition
substantially identical with a composition of said
25 resin potting.

30 14. A semiconductor device as claimed in
claim 11, wherein said circuit substrate is formed of
a glass epoxy.

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15. A semiconductor device as claimed in

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1 claim 11, wherein said circuit substrate is formed of
a polyimide film.

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16. A semiconductor device, comprising:
a semiconductor chip having a top surface,
said semiconductor chip carrying a first electrode;
a circuit substrate attached to a top
surface of said semiconductor chip, said circuit
substrate carrying thereon a predetermined conductor
pattern including a second electrode and a third
electrode;

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a spherical electrode provided on said
circuit substrate in correspondence to said third
electrode;

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a bonding wire electrically interconnecting
said second electrode of said predetermined conductor
pattern on said circuit substrate and said first
electrode on said semiconductor chip;

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a resin potting encapsulating said bonding
wire including said first and second electrodes;
a resin side wall cover covering a side wall
of said circuit substrate;

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said chip having a side wall substantially
flush to an outer surface of said resin side wall
cover, said side wall of said chip being substantially
perpendicular to a principal surface of said chip.

17. A semiconductor device as claimed in
claim 16, wherein said resin potting and said resin
side wall cover have a substantially identical
composition.

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